

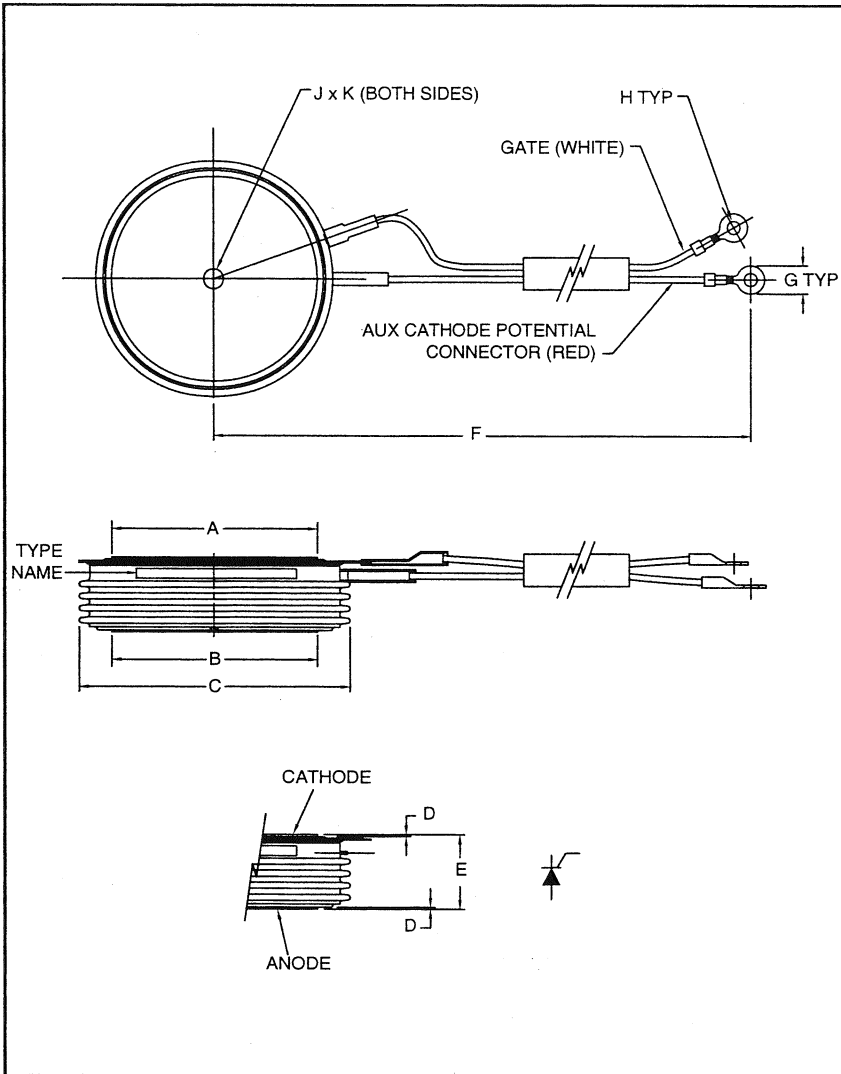
270 Pbm 4.4



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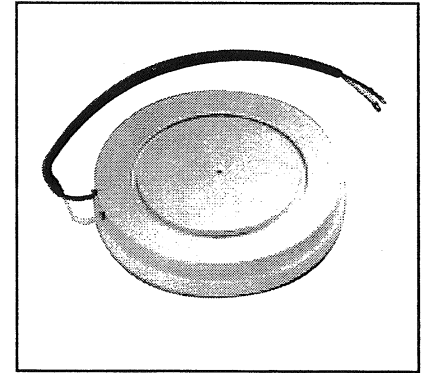
Mitsubishi Thyristor
FT1500AU-240

**Ultra High Voltage
Thyristor
1500 Amperes/12000 Volts**



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.13 Dia.	105.0 Dia.
B	4.13 Dia.	105.0 Dia.
C	6.5 Dia.	165.0 Dia.
D	0.2	0.40
E	1.38±0.02	35.0±0.5
F	17.99±0.39	457.0±10
G	0.30	7.5
H	0.17 Dia.	4.3 Dia.
J	0.14 Dia.	3.6±0.1 Dia.
K	0.09 Deep	2.2±0.1 Deep



Description:

Powerex Ultra High Voltage Thyristors are used in high voltage AC Switch and Static Var Compensator (SVC) applications.

Features:

- Average On-state Current ($I_{T(AV)} = 1500A$)
- Repetitive Peak Off-state Voltage ($V_{DRM} = 12000V$)
- Low On-state Voltage
- Press Pack Type

Applications:

- High Voltage AC Switch
- Static Var Compensator (SVC)

Ordering Information:

Example: Select the complete part module number you desire from the table below.

Device	Current Rating Amperes	Manu. Number	Type	Voltage Rating (x 50)
FT*	1500	A	U**	240

* Press Pack Thyristor
**Ultra High Voltage

Powerex, Inc., 200 Hillis Street, Youngwood, Pennsylvania 15697-1800 (724) 925-7272

FT1500AU-240
Ultra High Voltage Thyristor
 1500 Amperes/12000 Volts

Absolute Maximum Ratings, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Ratings	Symbol	FT1500AU-240	Units
Repetitive Peak Reverse Voltage	V_{RRM}	12000	Volts
Non-Repetitive Peak Reverse Voltage	V_{RSM}	12000	Volts
DC Reverse Voltage	$V_{R(DC)}$	9600	Volts
Repetitive Peak Off-state Voltage	V_{DRM}	12000	Volts
Non-Repetitive Peak Off-state Voltage	V_{DSM}	12000	Volts
RMS On-state Current	$I_{T(RMS)}$	2360	Amperes
Average On-state Current, $f = 60\text{Hz}$, Sine Wave $\theta = 180^\circ\text{C}$, $T_f = 88^\circ\text{C}$	$I_{T(AV)}$	1500	Amperes
Surge (Non-repetitive) On-state Current, One Half Cycle at 60Hz	I_{TSM}	34	kA
Current-squared, Time Integration, One Cycle at 60Hz	I^2t	4.8×10^6	A^2s
Critical Rate of Rise of On-state Current, $V_D = 1/2 V_{DRM}$, $I_G = 2.0\text{A}$, $T_j = 125^\circ\text{C}$	di_T/dt	100	$\text{A}/\mu\text{s}$
Peak Forward Gate Power Dissipation	P_{FGM}	30	Watts
Average Forward Gate Power Dissipation	$P_{FG(AV)}$	8.0	Watts
Peak Forward Gate Voltage	V_{FGM}	20	Volts
Peak Reverse Gate Voltage	V_{RGM}	10	Volts
Peak Forward Gate Current	I_{FGM}	6.0	Amperes
Junction Temperature	T_j	-40 to 125	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to 150	$^\circ\text{C}$
Mounting Force Required, Recommended Value 118	-	108 ~ 132	kN
Weight, Standard Value	-	4000	Grams
DC Off-state Voltage	$V_{D(DC)}$	9600	Volts

Electrical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

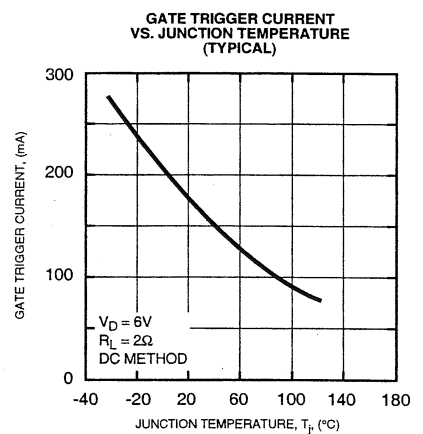
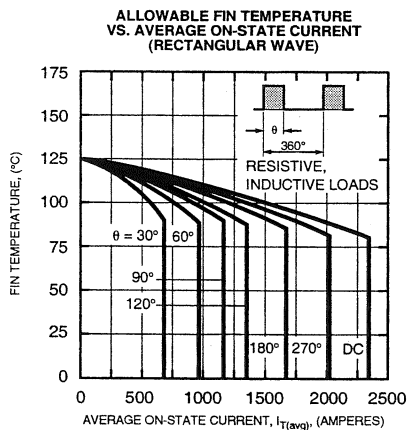
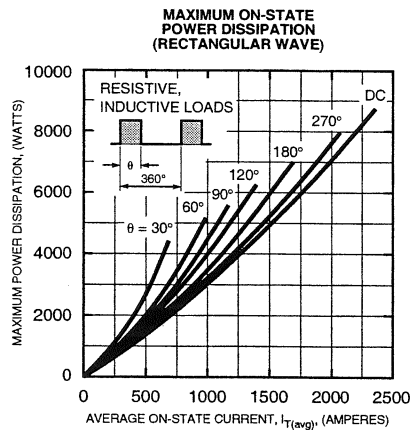
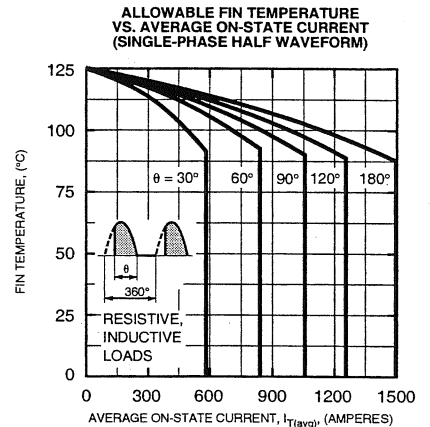
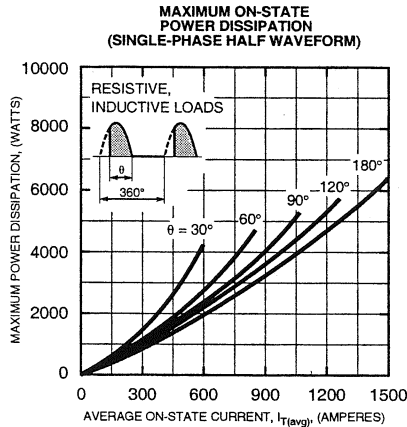
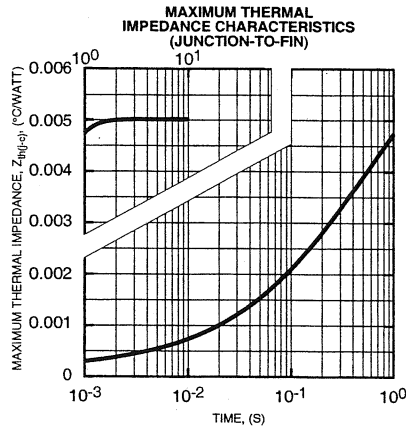
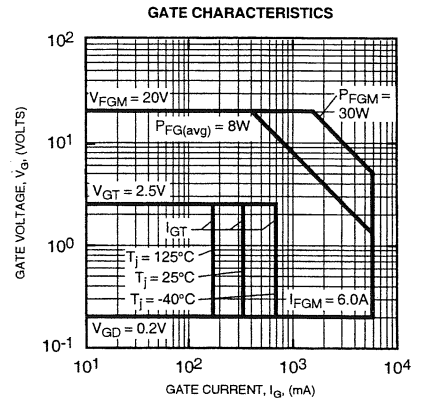
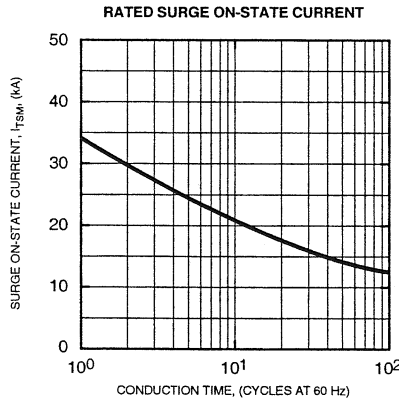
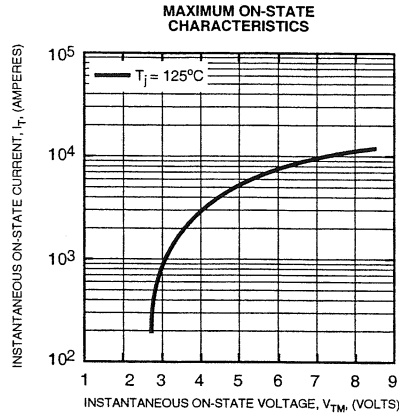
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Repetitive Peak Reverse Current	I_{RRM}	$T_j = 125^\circ\text{C}$, V_{RRM} Applied	-	-	1200	mA
Repetitive Peak Off-state Current	I_{DRM}	$T_j = 125^\circ\text{C}$, V_{DRM} Applied	-	-	1200	mA
On-state Voltage	V_{TM}	$T_j = 125^\circ\text{C}$, $I_{TM} = 3000\text{A}$, Instantaneous Measurement	-	-	4.0	Volts
Critical Rate of Rise of Off-state Voltage	dv/dt	$T_j = 125^\circ\text{C}$, $V_D = 1/2 V_{DRM}$	2000	-	-	$\text{V}/\mu\text{s}$
Gate Trigger Voltage	V_{GT}	$T_j = 25^\circ\text{C}$, $V_D = 6\text{V}$, $R_L = 2\Omega$	-	-	2.5	Volts
Gate Non-trigger Voltage	V_{GD}	$T_j = 125^\circ\text{C}$, $V_D = 1/2 V_{DRM}$	0.2	-	-	Volts
Gate Trigger Current	I_{GT}	$T_j = 25^\circ\text{C}$, $V_D = 6\text{V}$, $R_L = 2\Omega$	-	-	350	mA

Thermal and Mechanical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Fin	$R_{th(j-f)}$	-	-	-	0.005	$^\circ\text{C}/\text{W}$

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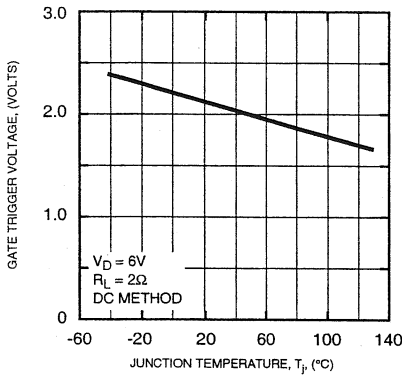
FT1500AU-240
Ultra High Voltage Thyristor
 1500 Amperes/12000 Volts



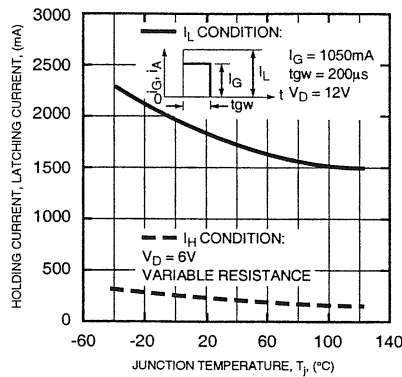
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FT1500AU-240
Ultra High Voltage Thyristor
 1500 Amperes/12000 Volts

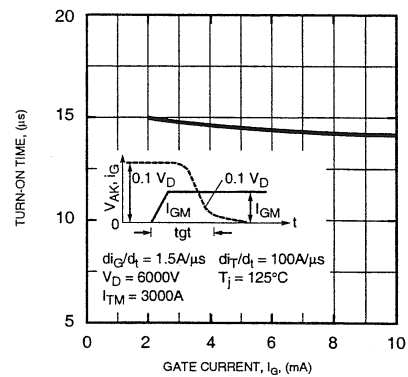
GATE TRIGGER VOLTAGE VS. JUNCTION TEMPERATURE (TYPICAL)



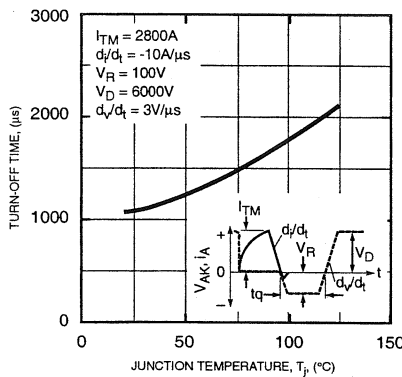
HOLDING CURRENT, LATCHING CURRENT VS. JUNCTION TEMPERATURE (TYPICAL)



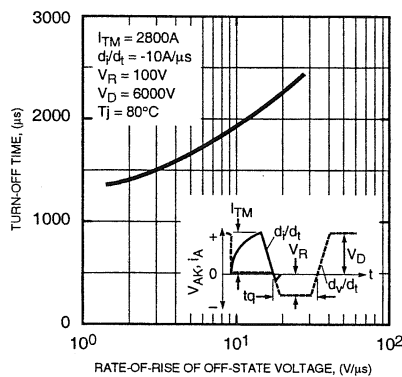
TURN-ON TIME VS. GATE CURRENT (TYPICAL)



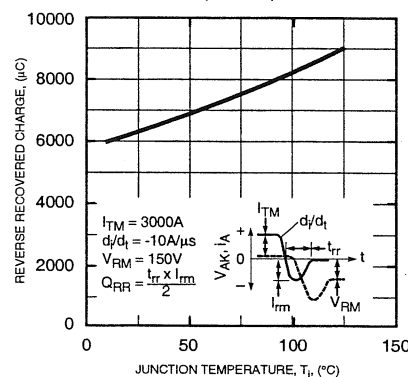
TURN-OFF TIME VS. JUNCTION TEMPERATURE (TYPICAL)



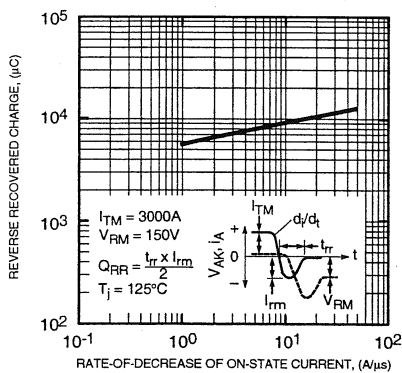
TURN-OFF TIME VS. RATE-OF-RISE OF OFF-STATE VOLTAGE (TYPICAL)



REVERSE RECOVERED CHARGE VS. JUNCTION TEMPERATURE (TYPICAL)



REVERSE RECOVERED CHARGE VS. RATE-OF-DECREASE OF ON-STATE CURRENT (TYPICAL)



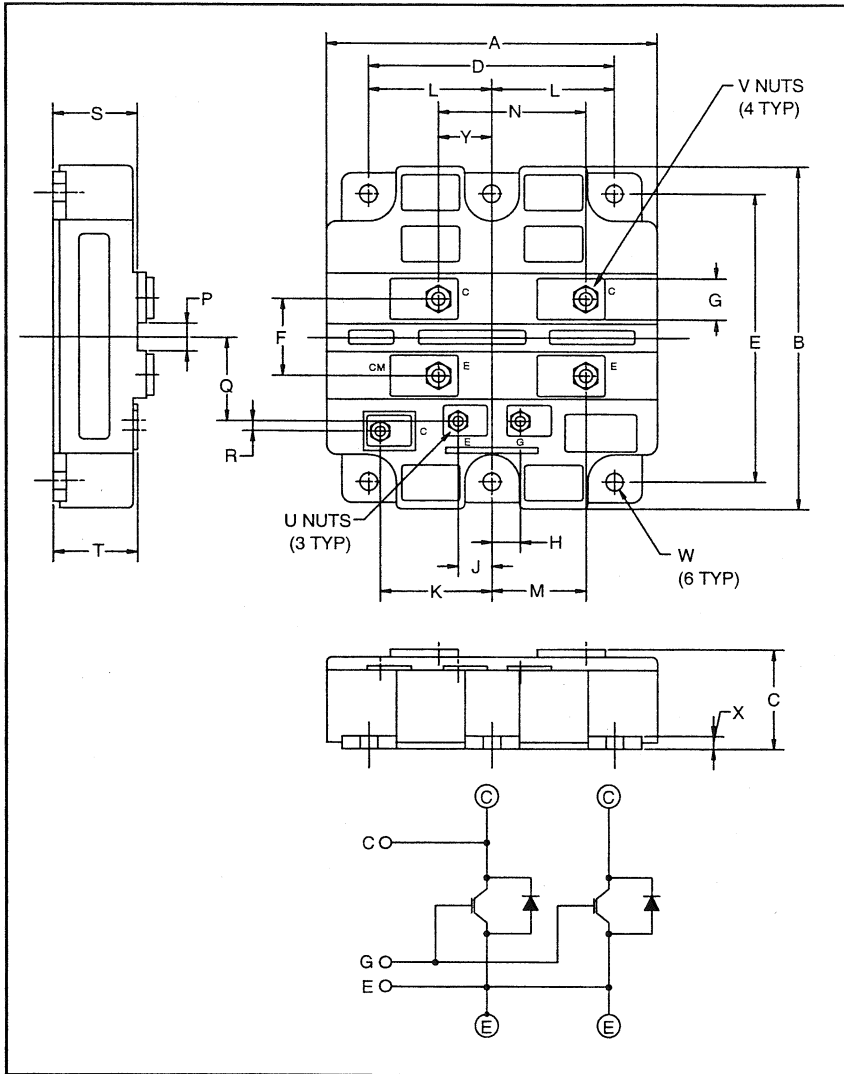
L10 Pbm 4.4



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CM400HB-90H

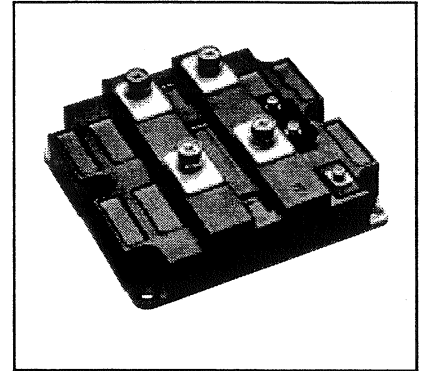
Single IGBTMOD™
HVIGBT
400 Amperes/4500 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	5.12	130.0
B	5.51	140.0
C	1.50	38.0
D	4.48	114.0
E	4.88±0.01	124.0±0.25
F	1.57	40.0
G	0.79	20.0
H	0.41	10.35
J	0.42	10.65
K	1.92	48.8
L	2.24±0.01	57.0±0.25
M	1.71	43.5

Dimensions	Inches	Millimeters
N	2.42	61.5
P	0.59	15.0
Q	1.57	40.0
R	0.20	5.2
S	1.16	29.5
T	1.10	28.0
U	M4 Metric	M4
V	M8 Metric	M8
W	0.28 Dia.	Dia.7.0
X	0.20	5.0
Y	0.71	18.0



Description:

Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of one IGBT Transistor with a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- Low Drive Power
- Low $V_{CE(sat)}$
- Super-Fast Recovery Free-Wheel Diode
- Isolated Baseplate for Easy Heat Sinking

Applications:

- Traction
- Medium Voltage Drive
- High Voltage Power Supplies

Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM400HB-90H is a 4500V (V_{CES}), 400 Ampere Single IGBTMOD™ Power Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	400	90



Powerex, Inc., 200 Hillis Street, Youngwood, Pennsylvania 15697-1800 (724) 925-7272

CM400HB-90H
Single IGBTMOD™ HVIGBT
400 Amperes/4500 Volts

Absolute Maximum Ratings, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Ratings	Symbol	CM400HB-90H	Units
Junction Temperature	T_j	-40 to 150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to 125	$^\circ\text{C}$
Collector-Emitter Voltage ($V_{GE} = 0\text{V}$)	V_{CES}	4500	Volts
Gate-Emitter Voltage ($V_{CE} = 0\text{V}$)	V_{GES}	± 20	Volts
Collector Current ($T_c = 25^\circ\text{C}$)	I_C	400	Amperes
Peak Collector Current (Pulse)	I_{CM}	800*	Amperes
Diode Forward Current** ($T_c = 25^\circ\text{C}$)	I_E	400	Amperes
Diode Forward Surge Current** (Pulse)	I_{EM}	800*	Amperes
Maximum Collector Dissipation ($T_c = 25^\circ\text{C}$, IGBT Part, $T_j \leq 125^\circ\text{C}$)	P_C	4300	Watts
Max. Mounting Torque M8 Terminal Screws	-	115	in-lb
Max. Mounting Torque M6 Mounting Screws	-	53	in-lb
Max. Mounting Torque M4 Auxiliary Terminal Screws	-	17	in-lb
Module Weight (Typical)	-	1.5	kg
Isolation Voltage (Charged Part to Baseplate, AC 60Hz 1 min.)	V_{iso}	6000	Volts

* Pulse width and repetition rate should be such that device junction temperature (T_j) does not exceed $T_{j(max)}$ rating.

**Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDI).

Static Electrical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	I_{CES}	$V_{CE} = V_{CES}, V_{GE} = 0\text{V}$	-	-	8.0	mA
Gate Leakage Current	I_{GES}	$V_{GE} = V_{GES}, V_{CE} = 0\text{V}$	-	-	0.5	μA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 40\text{mA}, V_{CE} = 10\text{V}$	4.5	6.0	7.5	Volts
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 400\text{A}, V_{GE} = 15\text{V}, T_j = 25^\circ\text{C}$	-	3.0	3.9*	Volts
		$I_C = 400\text{A}, V_{GE} = 15\text{V}, T_j = 125^\circ\text{C}$	-	3.3	-	Volts
Total Gate Charge	Q_G	$V_{CC} = 2250\text{V}, I_C = 400\text{A}, V_{GE} = 15\text{V}$	-	3.6	-	μC
Emitter-Collector Voltage**	V_{EC}	$I_E = 400\text{A}, V_{GE} = 0\text{V}$	-	4.0	5.2	Volts

* Pulse width and repetition rate should be such that device junction temperature rise is negligible.

**Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDI).



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CM400HB-90H
 Single IGBTMOD™ HVIGBT
 400 Amperes/4500 Volts

Dynamic Electrical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance	C_{ies}		–	72	–	nF
Output Capacitance	C_{oes}	$V_{GE} = 0V, V_{CE} = 10V$	–	5.3	–	nF
Reverse Transfer Capacitance	C_{res}		–	1.6	–	nF
Resistive	Turn-on Delay Time	$V_{CC} = 2250V, I_C = 400A,$ $V_{GE1} = V_{GE2} = 15V,$ $R_G = 22.5\Omega$	–	–	2.4	μs
Load	Rise Time		–	–	2.4	μs
Switching	Turn-off Delay Time		–	–	6.0	μs
Times	Fall Time	Resistive Load Switching Operation	–	–	1.2	μs
Diode Reverse Recovery Time**	t_{rr}	$I_E = 400A, di_E/dt = -800A/\mu s$	–	–	1.8	μs
Diode Reverse Recovery Charge**	Q_{rr}	$I_E = 400A, di_E/dt = -800A/\mu s$	–	160*	–	μC

* Pulse width and repetition rate should be such that device junction temperature rise is negligible.

**Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

Thermal and Mechanical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

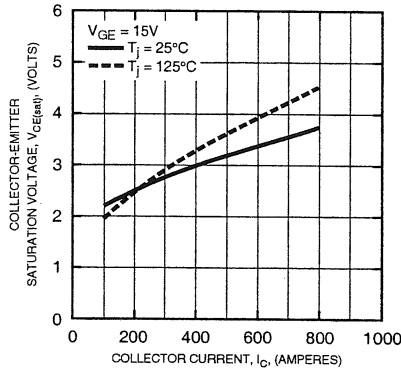
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c) Q}$	Per IGBT	–	–	0.023	K/W
Thermal Resistance, Junction to Case	$R_{th(j-c) D}$	Per FWDi	–	–	0.045	K/W
Contact Thermal Resistance, Case to Fin	$R_{th(c-f)}$	Per Module, Thermal Grease Applied	–	0.015	–	K/W



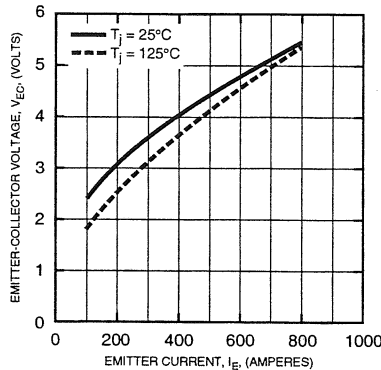
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CM400HB-90H
Single IGBTMOD™ HVIGBT
 400 Amperes/4500 Volts

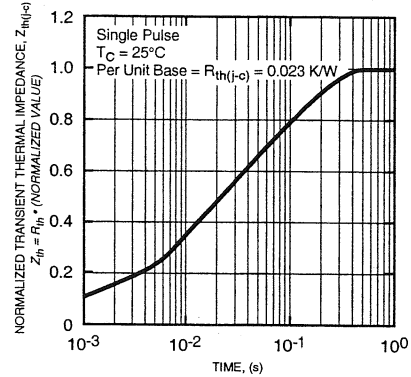
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



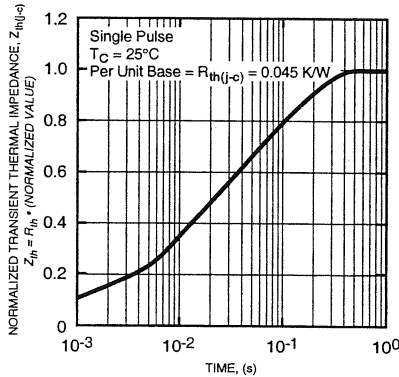
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



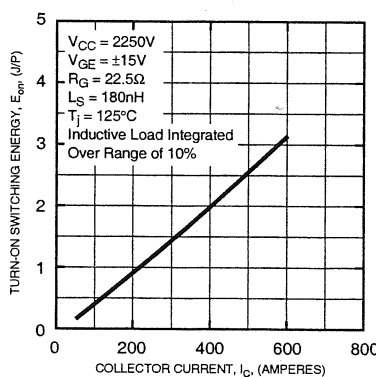
TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT)



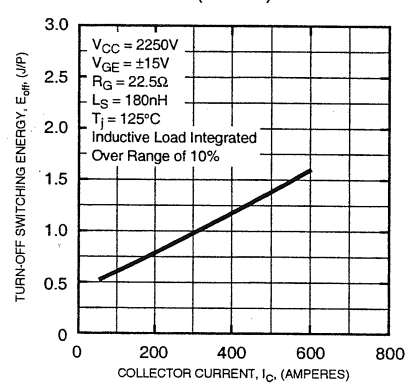
TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (FWD)



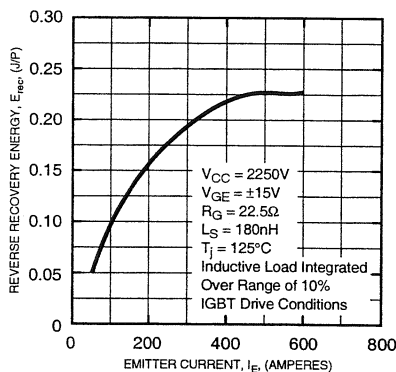
HALF-BRIDGE TURN-ON SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



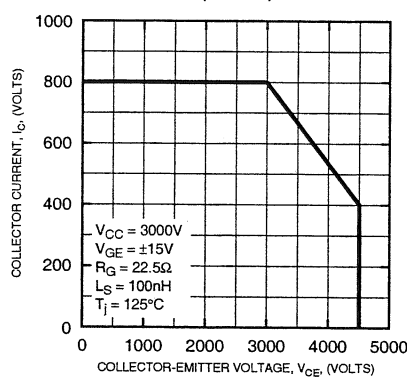
HALF-BRIDGE TURN-OFF SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



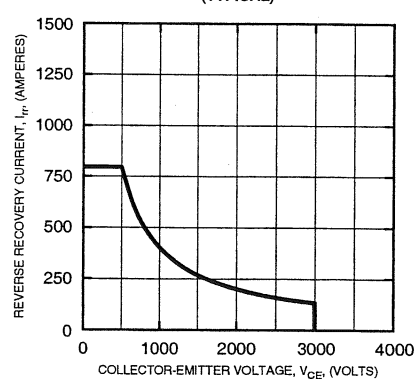
FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



TURN-ON SWITCHING SAFE OPERATING AREA (RBSOA) (TYPICAL)



DIODE REVERSE RECOVERY SAFE OPERATING AREA (TYPICAL)



PRELIMINARY SPECIFICATIONS

DE-375 301N35



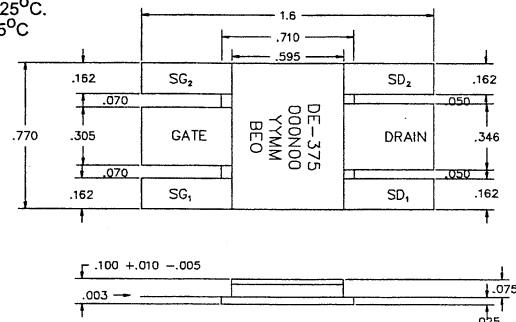
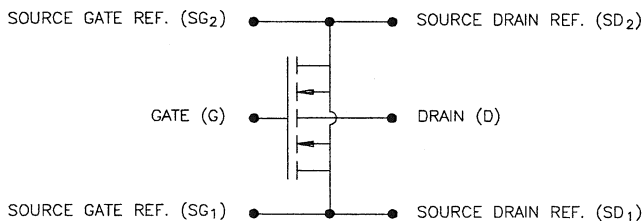
Directed Energy, Incorporated
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35A, 300V, 0.10Ω
 US Patents 4891686, 5640045
 Foreign Patents Pending
 (04/1999)

ELECTRICAL CHARACTERISTICS		MIN	TYP	MAX	UNITS	TEST CONDITIONS
V _{DSS}	Drain-Source Voltage	-	-	300	v	
BV _{DSS}	Drain-Source Breakdown Voltage	300	-	-	v	V _{GS} = 0, I _{DS} = 250μA (1)
V _{GS(th)}	Gate Threshold Voltage	2	3	4.5	V	V _{DS} = V _{GS} , I _D = 250μA (1)
V _{GS}	Gate-Source Voltage Continuous	-	-	±20	V	
I _{DC}	Drain Current Continuous	-	-	35	A	(1) (5) (6)
I _{DP}	Drain Current Pulsed	-	-	280	A	(2) (4) (5) (6)
g _{fs}	Forward Transconductance	-	29	-	S	V _{DS} = 50V, I _{DS} = .5I _{DC}
R _{DS(on)}	Static Drain-Source On-State Resistance	-	.10	-	Ω	V _{GS} = 15V, I _{DS} = .5I _{DC} (1) (5)
C _{iss}	Input Capacitance	-	3800	-	pF	V _{DS} = .8BV _{DSS}
C _{oss}	Output Capacitance	-	300	-	pF	f = 1.0MHz
C _{rss}	Reverse Transfer Capacitance	-	90	-	pF	(3)
t _{d(on)}	Turn-On Delay Time	-	6	-	ns	V _{DS} = .8BV _{DSS}
t _r	Rise Time	-	6	-	ns	I _{DS} = .5I _{DC}
t _{d(off)}	Turn-Off Delay Time	-	18	-	ns	Z _{GD} ≤ 1Ω
t _f	Fall Time	-	32	-	ns	(2)
SOURCE-DRAIN DIODE CHARACTERISTICS		MIN	TYP	MAX	UNITS	TEST CONDITIONS
I _{SC}	Continuous Source Current (Body Diode)	-	-	35	A	(1) (5)
I _{SP}	Pulse Source Current (Body Diode)	-	-	280	A	(2) (4) (5)
V _{SD}	Diode Forward Voltage	-	-	1.5	V	I _{SD} = .5I _{SC} , V _{GS} = 0 (1) (5)
t _{rr}	Reverse Recovery Time	-	800	-	ns	I _{SD} = .5I _{SC}
THERMAL CHARACTERISTICS		MIN	TYP	MAX	UNITS	TEST CONDITIONS
R _{θJC}	Junction to Case	-	.290	-	°C/W	(6)
R _{θJHS}	Junction to Heat Sink	-	.65	-	°C/W	(1) (6)
R _{θJHA}	Junction to Ambient	-	25	-	°C/W	Free Air Operation (6)
P _{D AMB}	Power Dissipation Free Air Operation	-	4.5	-	W	Free Air Operation T _J = 150°C (6) (7)
P _{D HS}	Power Dissipation W (Heat Sink)	-	200	-	W	T _J = 150°C (6) (8)
T _J & T _{sto}	Operating and Storage Temperature	-55	-	+150	°C	
T _L	Max. Lead Temp. for Soldering	-	-	300	°C	

- (1) DEI Test Fixture P/N 6040-0023.
- (2) DEI Test Fixture P/N 6040-1023.
- (3) DEI Test Fixture P/N 6040-2023.
- (4) Pulse width and repetition rate limited by junction temperature.

- (5) T_C = 25°C.
- (6) See mounting instructions.
- (7) T_{AMB} = 25°C.
- (8) T_{HS} = 25°C

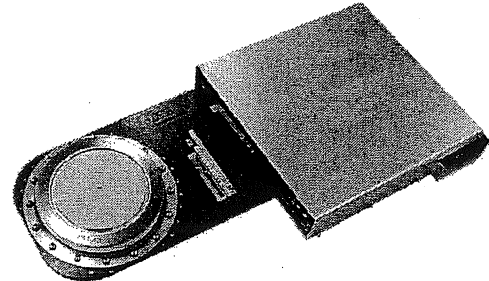


V_{DRM}	=	4500 V
I_{TGQM}	=	4000 A
I_{TSM}	=	32 kA
V_{T0}	=	1.40 V
r_{T}	=	0.325 m Ω
V_{Dclink}	=	2800 V

Asymmetric Integrated Gate- Commutated Thyristor **5SHY 35L4503**

Doc. No. 5SYA1228-01 Jan. 01

- Highest snubberless turn-off rating
- Suitable for series connection
- Fast response ($t_{\text{don}} < 3 \mu\text{s}$, $t_{\text{doff}} < 6 \mu\text{s}$)
- High reliability
- Very high EMI immunity
- Simple fibre optic control interface and status feedback
- Cosmic radiation withstand rating



Blocking

V_{DRM}	Repetitive peak off-state voltage	4500 V	$V_{\text{GR}} \geq 2V$
I_{DRM}	Repetitive peak off-state current	$\leq 50 \text{ mA}$	$V_{\text{D}} = V_{\text{DRM}} \quad V_{\text{GR}} \geq 2V$
V_{Dclink}	Permanent DC voltage for 100 FIT failure rate	2800 V	Ambient cosmic radiation at sea level in open air.

Mechanical data (see Fig. 8)

F_{m}	Mounting force	min.	36 kN	
		max.	44 kN	
D_{p}	Pole-piece diameter		85 mm	$\pm 0.1 \text{ mm}$
H	Housing thickness		26 mm	$\pm 0.5 \text{ mm}$
m	Weight IGCT		3.30 kg	
D_{s}	Surface creepage distance	\geq	33 mm	Anode to Gate
D_{a}	Air strike distance	\geq	13 mm	Anode to Gate
l	Length IGCT		451 mm	$\pm 1.0 \text{ mm}$
h	Height IGCT		40 mm	$\pm 1.0 \text{ mm}$
w	Width IGCT		213 mm	$\pm 1.0 \text{ mm}$

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GCT Data

On-state (see Fig. 2, 3, 4)

I_{TAVM}	Max. average on-state current	1345 A	Half sine wave, $T_C = 85\text{ °C}$		
I_{TRMS}	Max. RMS on-state current	2110 A			
I_{TSM}	Max. peak non-repetitive surge current	32 kA	$t_p =$	10 ms	$T_j = 125\text{ °C}$ After surge: $V_D = V_R = 0V$
		47 kA	$t_p =$	1 ms	
I^2t	Limiting load integral	$5.1 \cdot 10^6\text{ A}^2\text{s}$	$t_p =$	10 ms	
		$1.1 \cdot 10^6\text{ A}^2\text{s}$	$t_p =$	1 ms	
V_T	On-state voltage	$\leq 2.70\text{ V}$	$I_T =$	4000 A	$T_j = 125\text{ °C}$
V_{T0}	Threshold voltage	1.40 V	$I_T =$	1000 - 4000 A	
r_T	Slope resistance	0.325 m Ω			

Turn-on switching

di/dt_{crit}	Max. rate of rise of on-state current	1000 A/ μs	$f = 500\text{ Hz}$	$T_j = 125\text{ °C}$
			$I_T = 4000\text{ A}$	$V_D = 2500\text{ V}$
t_{don}	Turn-on delay time	$\leq 3\text{ }\mu\text{s}$	$V_D = 2500\text{ V}$	$T_j = 125\text{ °C}$
t_r	Rise time	$\leq 1\text{ }\mu\text{s}$	$I_T = 4000\text{ A}$	
$t_{on(min)}$	Min. on-time	10 μs	$R_s = 0.8\text{ }\Omega$	$L_i = 2.2\text{ }\mu\text{H}$
E_{on}	Turn-on energy per pulse	$\leq 1.5\text{ J}$	$C_{CL} = 6.0\text{ }\mu\text{F}$	$L_{CL} = 0.3\text{ }\mu\text{H}$

Turn-off switching (see Fig. 5, 6)

I_{TGQM}	Max. controllable turn-off current	4000 A	$V_{DM} \leq V_{DRM}$	$T_j = 125\text{ °C}$
			$V_D = 2500\text{ V}$	$L_{CL} = 0.3\text{ }\mu\text{H}$
t_{doff}	Turn-off delay time	$\leq 6.0\text{ }\mu\text{s}$	$V_D = 2500\text{ V}$	$V_{DM} \leq V_{DRM}$
t_f	Fall time	$\leq 1.0\text{ }\mu\text{s}$	$T_j = 125\text{ °C}$	$R_s = 0.8\text{ }\Omega$
$t_{off(min)}$	Min. off-time	10 μs	$I_{TGQ} = 4000\text{ A}$	$L_i = 2.2\text{ }\mu\text{H}$
E_{off}	Turn-off energy per pulse	$\leq 19.5\text{ J}$	$C_{CL} = 6.0\text{ }\mu\text{F}$	$L_{CL} = 0.3\text{ }\mu\text{H}$

Gate Unit

Power supply (see Fig. 7 to 9)			
V_{GDC}	Gate Unit voltage	$20 \pm 0.5 V_{DC}$	Without galvanic isolation to power circuit.
P_{Gin}	Gate Unit power consumption	$\leq 52 W$	$f_s = 500 Hz$, $I_{TQAV} = 1000 A$, $\delta = 0.5$
X1	Gate Unit power connector	AMP, Type 640389-4, MTA 156, friction lock, right angle ^{Note 1}	
Optical control input/output (see Fig. 8 to 10)			
P_{onCS}	Optical input power	$> -21 dBm$	Valid for 1mm plastic optical fibre (POF)
P_{offCS}	Optical noise power	$< -40 dBm$	
P_{onSF}	Optical output power	$> -19 dBm$	
P_{offSF}	Optical noise power	$< -50 dBm$	
t_{GLITCH}	Pulse width threshold	$\leq 300 ns$	Max. pulse width without response
CS	Receiver for command signal	Agilent, Type HFBR-2528 ^{Note 2}	
SF	Transmitter for status feedback	Agilent, Type HFBR-1528 ^{Note 2}	

Note 1: AMP, www.amp.com

Note 2: Agilent Technologies, www.semiconductor.agilent.com

Thermal

T_j	Operating junction temperature range	0...125 °C		
T_{stg}	Storage temperature range	-40...85 °C		
T_{amb}	Ambient operational temperature range	0...50 °C		
R_{thJC}	Thermal resistance junction to case	≤ 12 K/kW		Double side cooled
		≤ 20 K/kW		Anode side cooled
		≤ 30 K/kW	Cathode side cooled	
R_{thCH}	Thermal resistance case to heatsink	≤ 6 K/kW	Double side cooled	
		≤ 3 K/kW	Single side cooled	

Analytical function for transient thermal impedance.

$$Z_{thJC}(t) = \sum_{i=1}^n R_i(1 - e^{-t/\tau_i})$$

i	1	2	3	4
$R_i(K/kW)$	5.4	4.5	1.7	0.4
$\tau_i(s)$	1.2	0.17	0.01	0.001
$F_M = 36... 44$ kN Double side cooled				

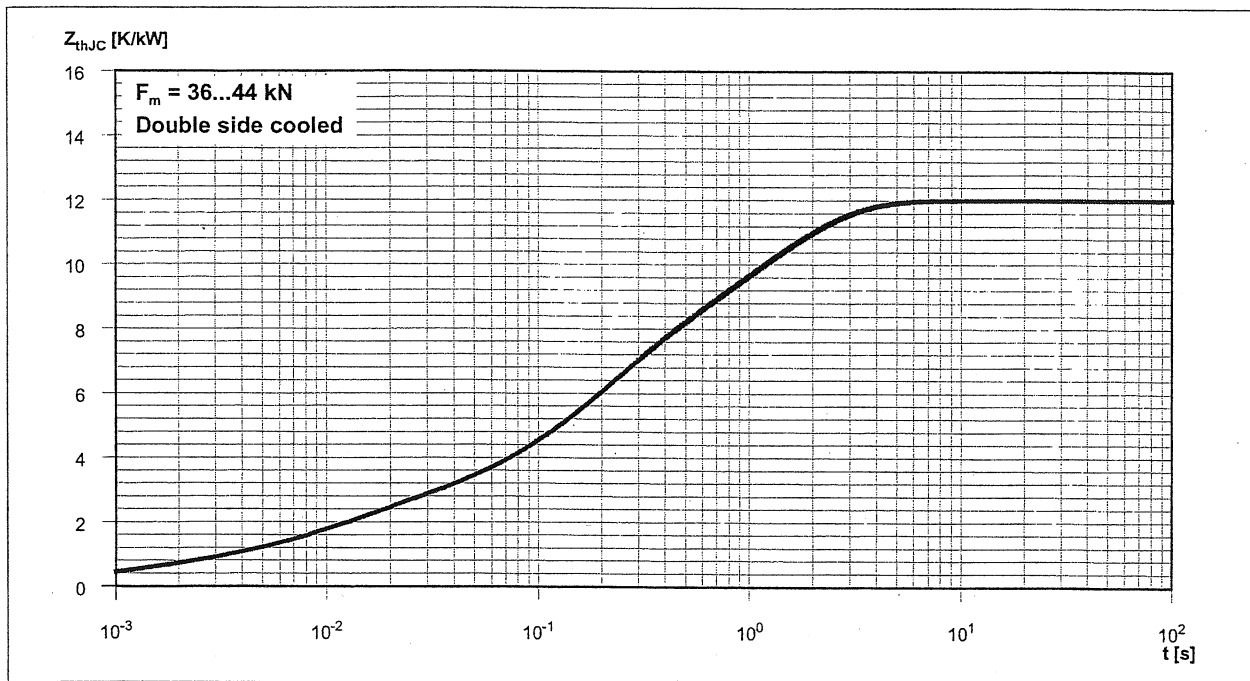


Fig. 1 Transient thermal impedance (junction-to-case) versus time (max. values).

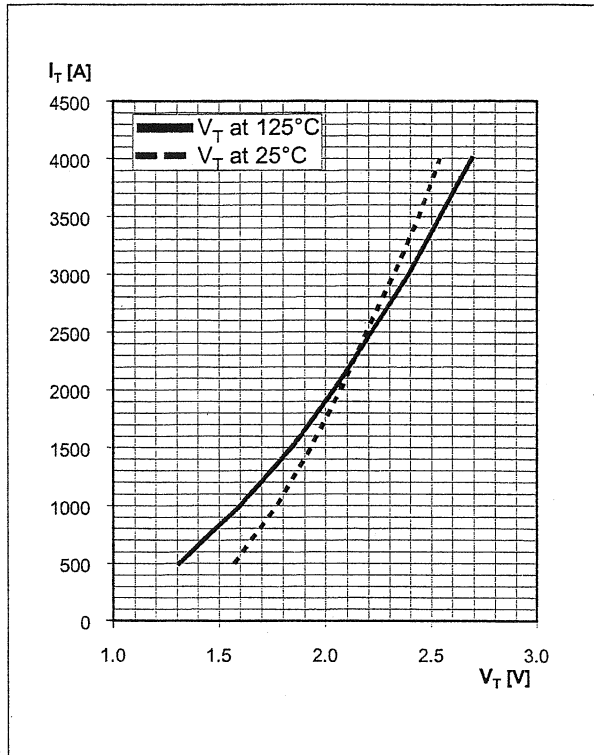


Fig. 2 GCT on-state characteristics.

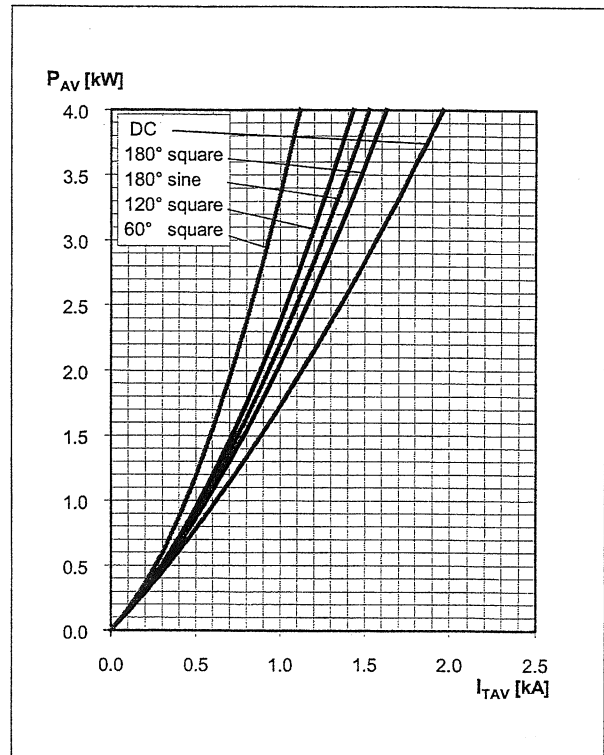


Fig. 3 Average on-state power dissipation versus on-state current.

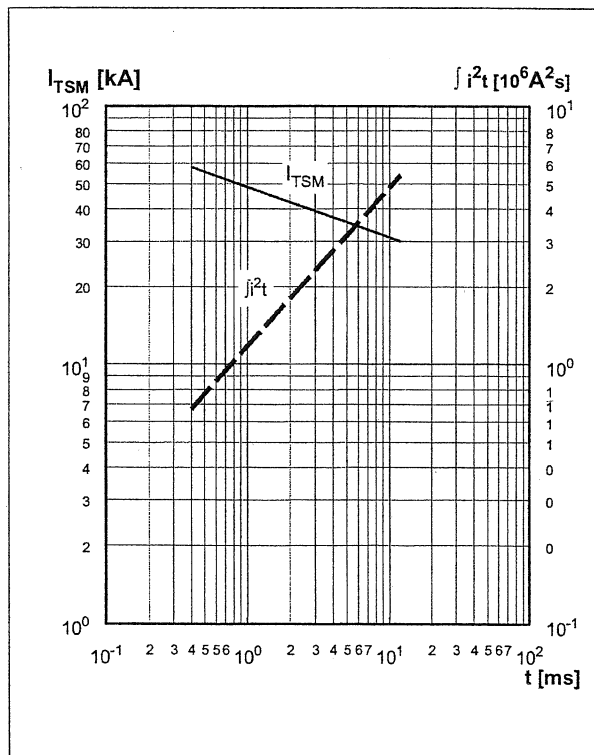


Fig. 4 Surge current and fusing integral versus

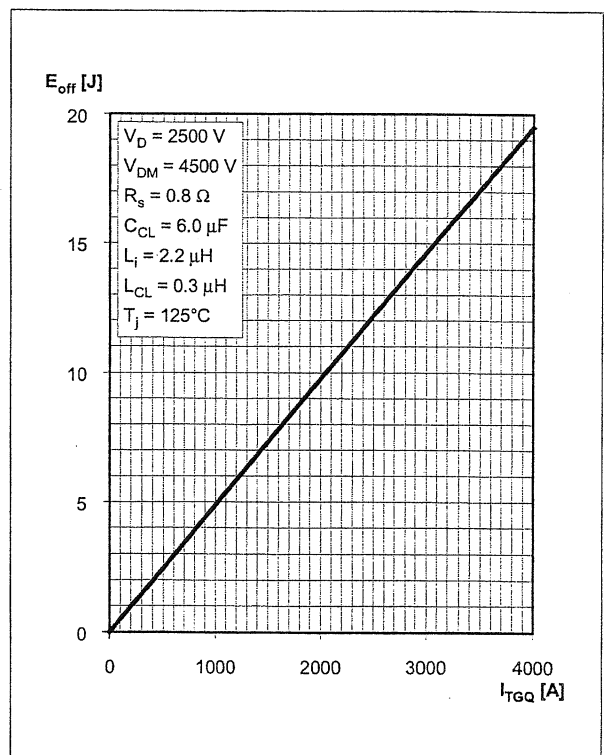


Fig. 5 GCT turn-off energy per pulse versus

pulse width.

turn-off current.

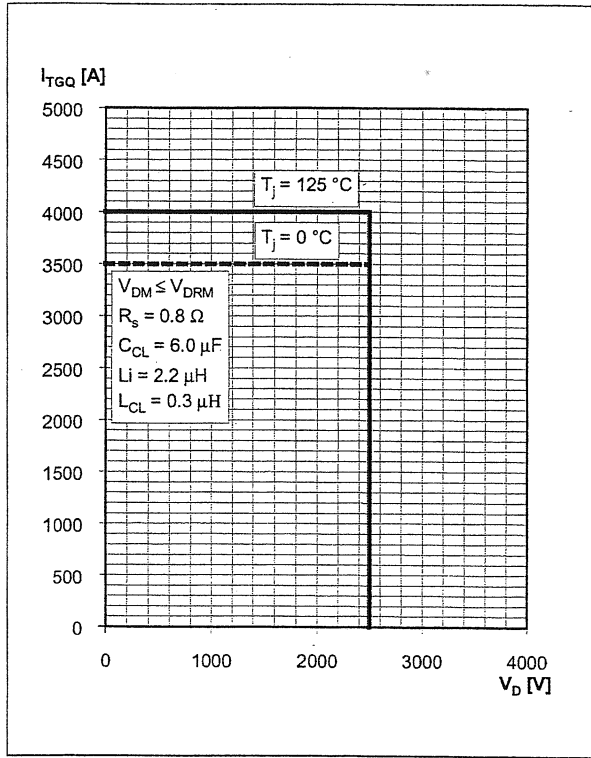


Fig. 6 Max. repetitive turn-off current versus turn-off voltage.

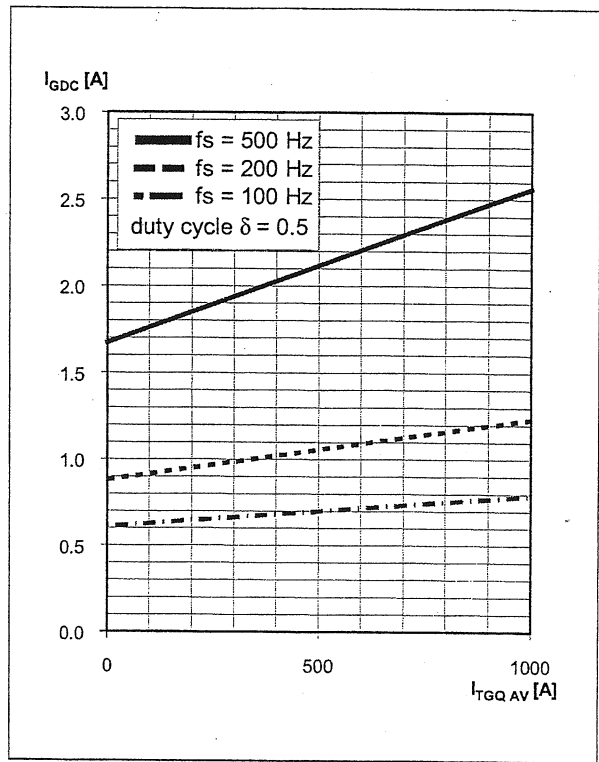


Fig. 7 Gate Unit Supply current.

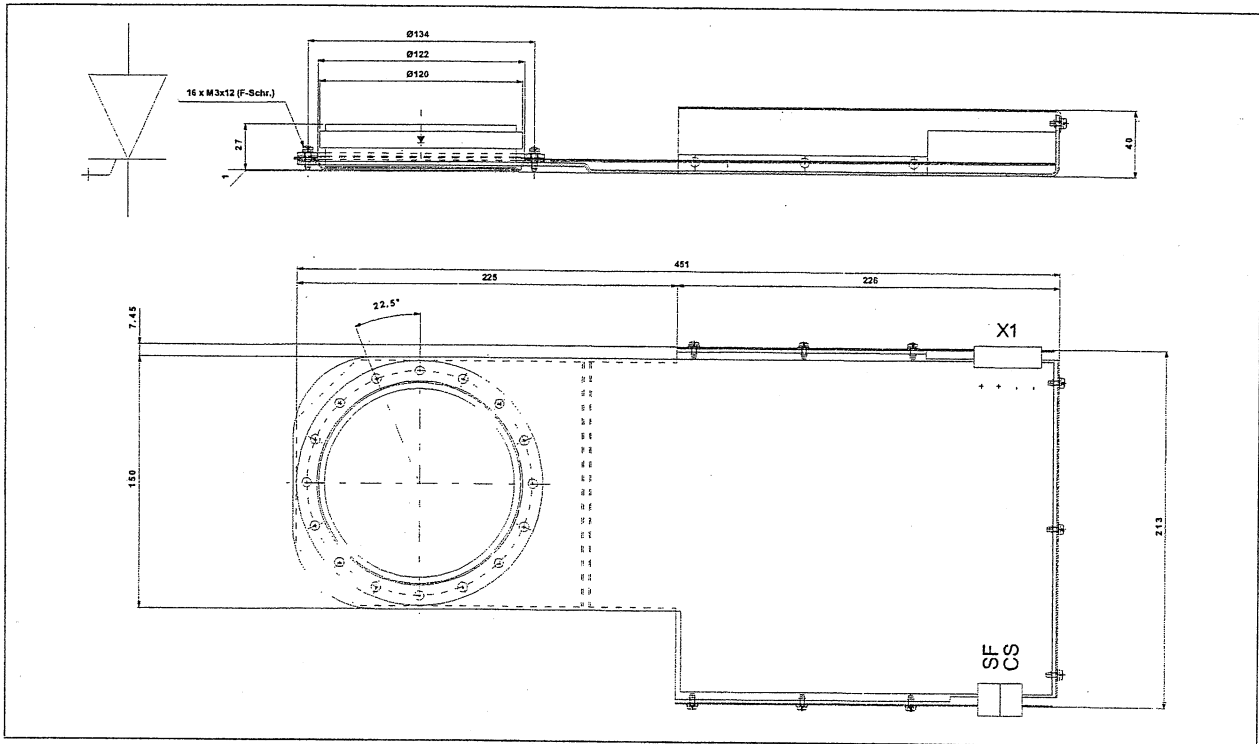


Fig. 8 Outline drawing. All dimensions are in millimeters and represent nominal values unless stated otherwise.

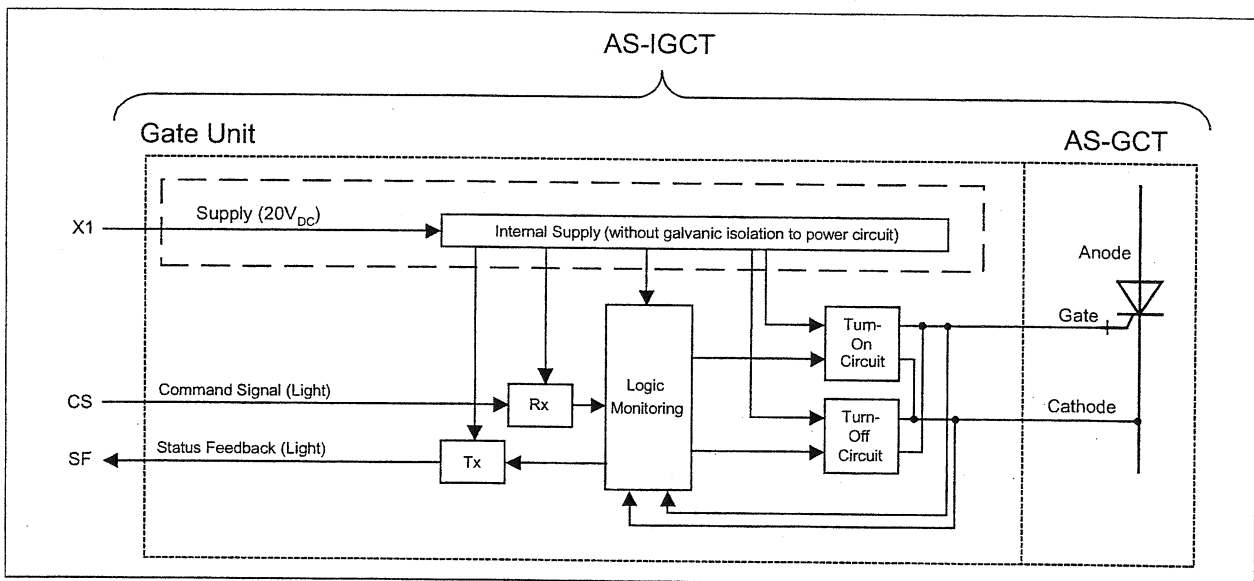


Fig. 9 Block diagram.

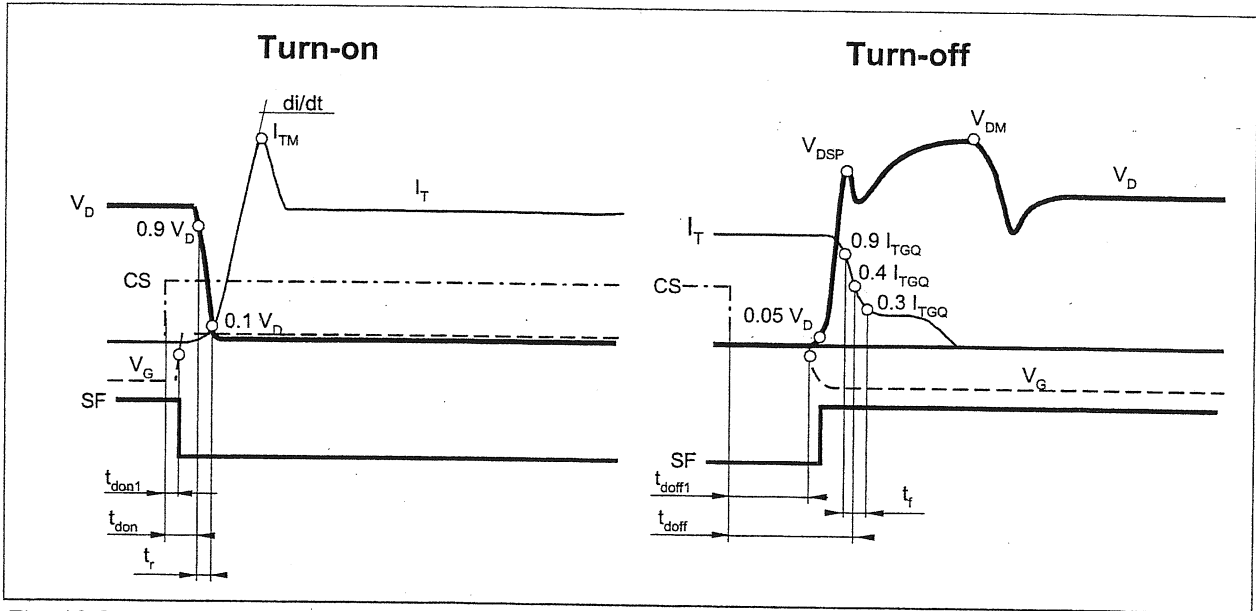


Fig. 10 General current and voltage waveforms with IGCT - specific symbols.

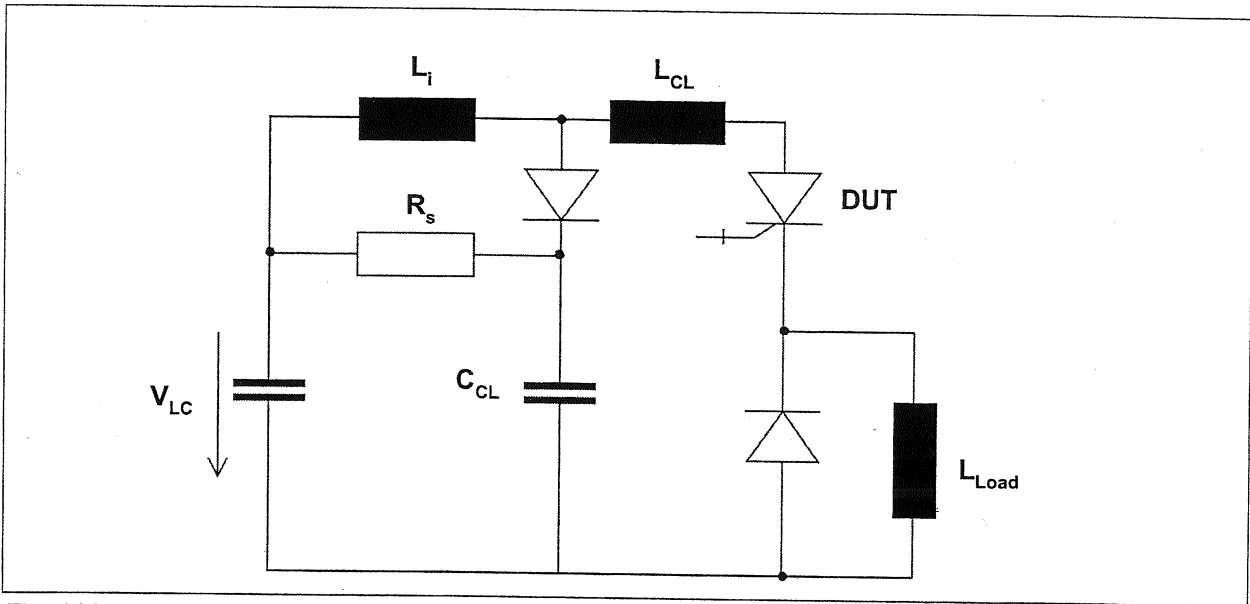


Fig. 11 Test circuit.

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